

ABSTRACT OF THE DISCLOSURE

A tape circuit board for manufacturing a fine pitch semiconductor chip package, a method for manufacturing the tape circuit board, and a semiconductor chip package using the tape circuit board are provided. The tape circuit board includes an insulating base film having a first surface and a second surface. An adhesive layer is formed on the first surface of the base film. Further, wiring patterns are formed on the adhesive layer. Conductive bumps extend through the base film and the adhesive layer and are connected to the wiring patterns. The conductive bumps extend above the second surface of the base film.